IN THE CLAIMS

Please amend the claims as follows:

1. (Currently Amended) A method of manufacturing a multilayer circuit board, in which a plurality of printed boards are stacked and pressed into a multilayer circuit board, each printed board having a conductor layer on one side of an insulating layer, the method comprising:

preparing a plurality of printed boards with respective copper foils, each printed board being made through the step of forming a via hole in an insulating substrate by laser processing from an insulating layer side so that the via hole extends in a direction of thickness of the insulating substrate so as to reach the conductive layer, the insulating substrate comprising a one-side copper-clad laminate wherein a plated conductor is formed in the via hole by electroplating using a copper foil as one electrode in a state in which the copper foil is covered by a protective film, a conductive bump is formed on the plated conductor, ~~and~~ a bonding layer is formed at the insulating layer side, and the protective layer is stripped from the copper foil;

etching the copper foil of at least one printed board of the plurality of printed boards so that a printed board with a conductor circuit is formed;

stacking the printed board with the conductor circuit and a second printed board of the plurality of printed boards, wherein the insulating layer side of the second printed board faces the etched copper foil of the printed board with the conductor circuit;

stacking an outermost conductor layer made of a copper foil on the insulating layer side of the printed board with the conductor circuit with a bonding layer being interposed

therebetween; and

integrating the outermost conductor layer, the printed board with the conductor circuit, and the second printed board by one time of pressing and thereafter, etching the copper foils on opposite surfaces, thereby obtaining the multilayer circuit board.

2. (Previously Presented) The method according to claim 1, wherein a plurality of the printed boards with the respective conductor circuits are formed.

3. (Previously Presented) The method according to claim 1, wherein conductive bump projects from an upper surface of the insulating substrate.

4. (Previously Presented) The method according to claim 1, wherein the conductive bump is made from a material with a low melting point.

5. (Previously Presented) The method according to claim 1, wherein the plated conductor filling the via hole has an amount determined so that an upper face thereof is lower than the surface of the insulating substrate.

6. (Previously Presented) The method according to claim 1, wherein the insulating substrate is made of a glass-cloth epoxy resin.

7. (Previously Presented) The method according to claim 2, wherein the insulating substrate is made of a glass-cloth epoxy resin.

8. (Previously Presented) The method according to claim 1, wherein the plated conductor filling the via hole has an amount determined so that the plated conductor does not extend above the surface of the insulating substrate.

9. (Previously Presented) The method according to claim 1, wherein the outermost conductor layer is not attached to an insulator or a bonding material prior to the step of

stacking the outermost conductor layer on the insulating layer side of the printed board with the conductor circuit.

10. (Currently Amended) A method of manufacturing a multilayer circuit board, in which a plurality of printed boards are stacked and pressed into a multilayer circuit board, each printed board having a conductor layer on one side of an insulating layer, the method comprising:

stacking the printed boards with a bonding layer being interposed between the printed boards, each printed board having a via hole extending through the insulating substrate to the conductor layer, the via hole being filled with a plated conductor by electroplating using a copper foil as one electrode in a state in which the copper foil is covered by a protective film, the plated conductor filling the via hole has an amount determined so that the plated conductor does not extend above the surface of the insulating substrate, the plated conductor being formed with a conductive bump extending through the bonding layer so that the conductive bump is connected to the conductor layer of another stacked printed board, and the protective layer being stripped from the copper foil;

stacking an outermost conductor layer on an insulating layer side of a first outermost printed board with a bonding layer being interposed therebetween; and

pressing the stack so that the printed boards and the outermost conductor layer are bonded together, the first outermost printed board being disposed with the insulating layer side being directed outward.

11. (Previously Presented) The method according to claim 10, wherein the stack of printed boards includes a second outermost printed board disposed with a conductor layer

side being directed outward, the conductor layer being pressed under a condition where the conductor layer has a uniform thickness all over.

12. (Previously Presented) The method according to claim 10, wherein the conductive bump projects from an upper surface of the insulating substrate.

13. (Previously Presented) The method according to claim 10, wherein the conductive bump is made from a material with a low melting point.

14. (Previously Presented) The method according to claim 10, wherein the insulating substrate is made of a glass-cloth epoxy resin.

15. (New) The method according to claim 1, wherein, during stacking of the printed board with the conductor circuit and the second printed board, the second printed board is a one-side copper-clad laminate having a copper foil over an entire surface thereof.